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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Applicant: Xiaowei Deng, et al.

Docket Number: TI-33969

Serial No.: 10/618,473

Art Unit: 2824

Filed: 07/11/03

Examiner: Van Thu T. Nguyen

For: System for Reducing Row Periphery Power Consumption  
in Memory Devices

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NAME OF INVENTOR(S): Xiaowei Deng, et al.	
RECEIPT DATE & SERIAL NO.: Serial No.: 10/618,473 Filing Date: 07/11/03	
TITLE OF INVENTION: System for Reducing Row Periphery Power Consumption in Memory Devices	
TI FILE NO.: TI-33969	DEPOSIT ACCT. NO.: 20-0668
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Texas Instruments Incorporated  
PO Box 655474, M/S 3999  
Dallas, TX 75265-5474